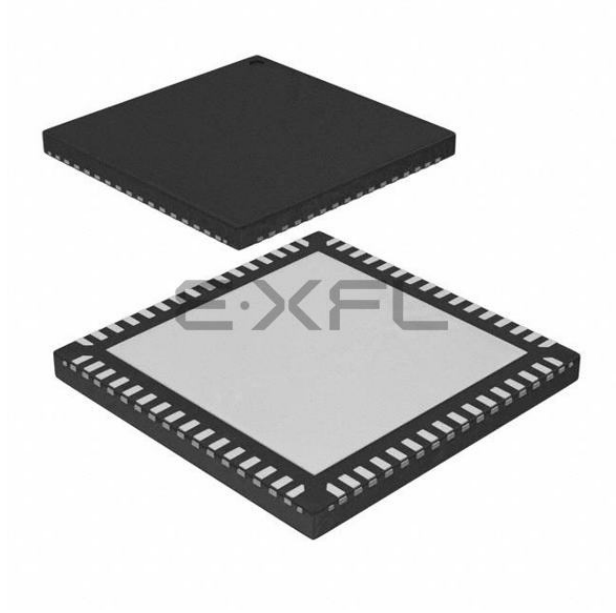


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	52
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 20x12b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsamd20j18a-mut

1. Description

The Atmel® | SMART™ SAM D20 is a series of low-power microcontrollers using the 32-bit ARM® Cortex®-M0+ processor, and ranging from 32- to 64-pins with up to 256KB Flash and 32KB of SRAM. The SAM D20 devices operate at a maximum frequency of 48MHz and reach 2.46 CoreMark/MHz. They are designed for simple and intuitive migration with identical peripheral modules, hex compatible code, identical linear address map and pin compatible migration paths between all devices in the product series. All devices include intelligent and flexible peripherals, Atmel Event System for inter-peripheral signaling, and support for capacitive touch button, slider and wheel user interfaces.

The SAM D20 devices provide the following features: In-system programmable Flash, eight-channel Event System, programmable interrupt controller, up to 52 programmable I/O pins, 32-bit real-time clock and calendar, up to eight 16-bit Timer/Counters (TC) . The timer/counters can be configured to perform frequency and waveform generation, accurate program execution timing or input capture with time and frequency measurement of digital signals. The TCs can operate in 8- or 16-bit mode, selected TCs can be cascaded to form a 32-bit TC. The series provide up to six Serial Communication Modules (SERCOM) that each can be configured to act as an USART, UART, SPI, I^2C up to 400kHz, up to twenty-channel 350ksps 12-bit ADC with programmable gain and optional oversampling and decimation supporting up to 16-bit resolution, one 10-bit 350ksps DAC, two analog comparators with window mode, Peripheral Touch Controller supporting up to 256 buttons, sliders, wheels and proximity sensing; programmable Watchdog Timer, brown-out detector and power-on reset and two-pin Serial Wire Debug (SWD) program and debug interface.

All devices have accurate and low-power external and internal oscillators. All oscillators can be used as a source for the system clock. Different clock domains can be independently configured to run at different frequencies, enabling power saving by running each peripheral at its optimal clock frequency, and thus maintaining a high CPU frequency while reducing power consumption.

The SAM D20 devices have two software-selectable sleep modes, idle and standby. In idle mode the CPU is stopped while all other functions can be kept running. In standby all clocks and functions are stopped expect those selected to continue running. The device supports SleepWalking. This feature allows the peripheral to wake up from sleep based on predefined conditions, and thus allows the CPU to wake up only when needed, e.g. when a threshold is crossed or a result is ready. The Event System supports synchronous and asynchronous events, allowing peripherals to receive, react to and send events even in standby mode.

The Flash program memory can be reprogrammed in-system through the SWD interface. The same interface can be used for non-intrusive on-chip debug of application code. A boot loader running in the device can use any communication interface to download and upgrade the application program in the Flash memory.

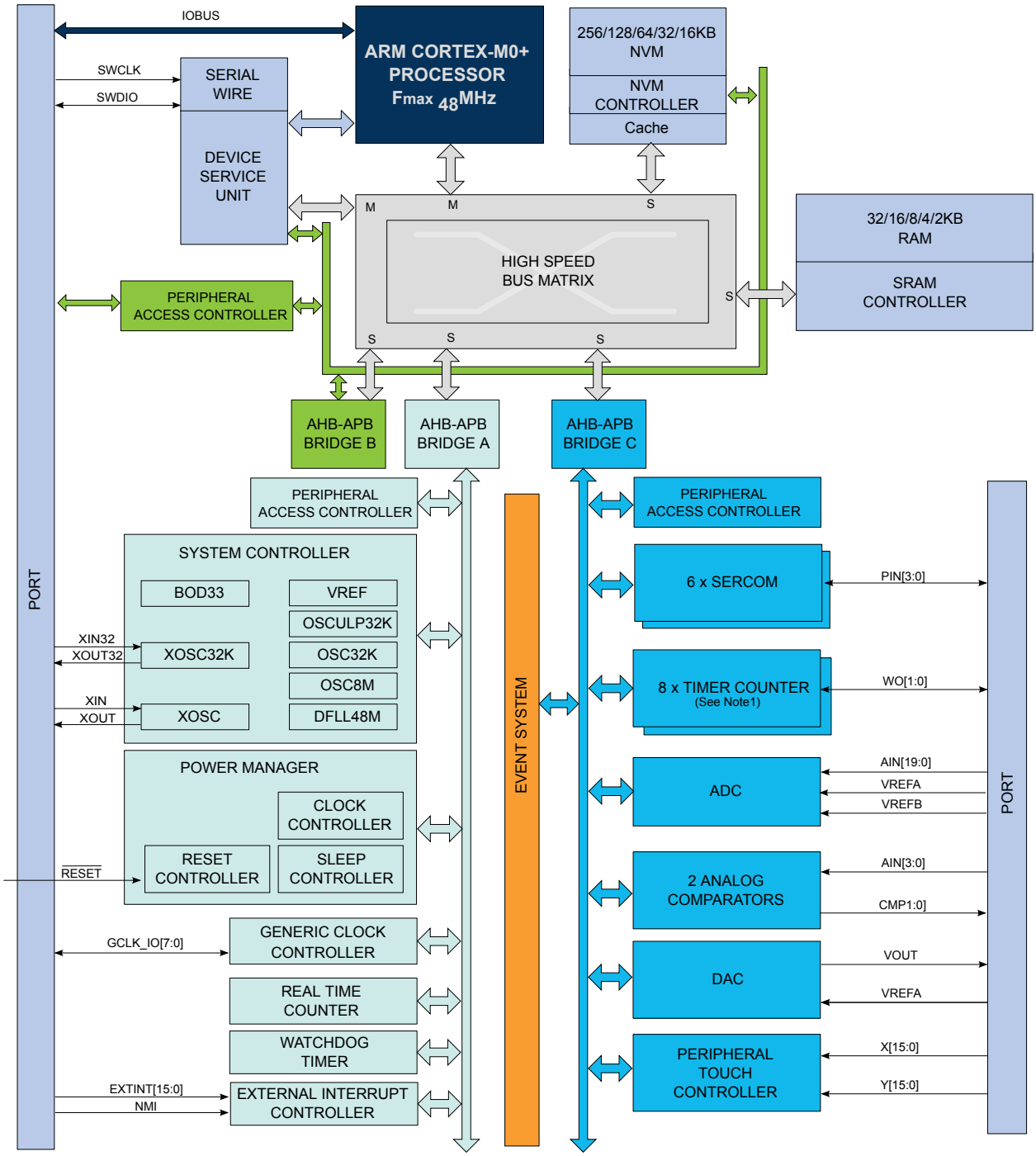
The SAM D20 devices are supported with a full suite of program and system development tools, including C compilers, macro assemblers, program debugger/simulators, programmers and evaluation kits.

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD20E15A-AU	32K	4K	TQFP32	Tray
ATSAMD20E15A-AUT				Tape & Reel
ATSAMD20E15A-AN				Tray
ATSAMD20E15A-ANT				Tape & Reel
ATSAMD20E15A-MU			QFN32	Tray
ATSAMD20E15A-MUT				Tape & Reel
ATSAMD20E15A-MN				Tray
ATSAMD20E15A-MNT				Tape & Reel
ATSAMD20E16A-AU	64K	8K	TQFP32	Tray
ATSAMD20E16A-AUT				Tape & Reel
ATSAMD20E16A-AN				Tray
ATSAMD20E16A-AFT				Tape & Reel
ATSAMD20E16A-MU			QFN32	Tray
ATSAMD20E16A-MUT				Tape & Reel
ATSAMD20E16A-MN				Tray
ATSAMD20E16A-MNT				Tape & Reel
ATSAMD20E17A-AU	128K	16K	TQFP32	Tray
ATSAMD20E17A-AUT				Tape & Reel
ATSAMD20E17A-AN				Tray
ATSAMD20E17A-ANT				Tape & Reel
ATSAMD20E17A-MU			QFN32	Tray
ATSAMD20E17A-MUT				Tape & Reel
ATSAMD20E17A-MN				Tray
ATSAMD20E17A-MNT				Tape & Reel
ATSAMD20E18A-AU	256K	32K	TQFP32	Tray
ATSAMD20E18A-AUT				Tape & Reel
ATSAMD20E18A-AN				Tray
ATSAMD20E18A-AFT				Tape & Reel
ATSAMD20E18A-MU			QFN32	Tray
ATSAMD20E18A-MUT				Tape & Reel
ATSAMD20E18A-MN				Tray
ATSAMD20E18A-MNT				Tape & Reel

Device Variant	DID.DEVSEL	Device ID (DID)
SAMD20E14A	0x0E	0x1000130E
Reserved	0x0F	
SAMD20G18U	0x10	0x10001310
SAMD20G17U	0x11	0x10001311
Reserved	0x12 - 0xFF	

Note: The device variant (last letter of the ordering number) is independent of the die revision (DSU.DID.REVISION): The device variant denotes functional differences, whereas the die revision marks evolution of the die. The device variant denotes functional differences, whereas the die revision marks evolution of the die.

4. Block Diagram

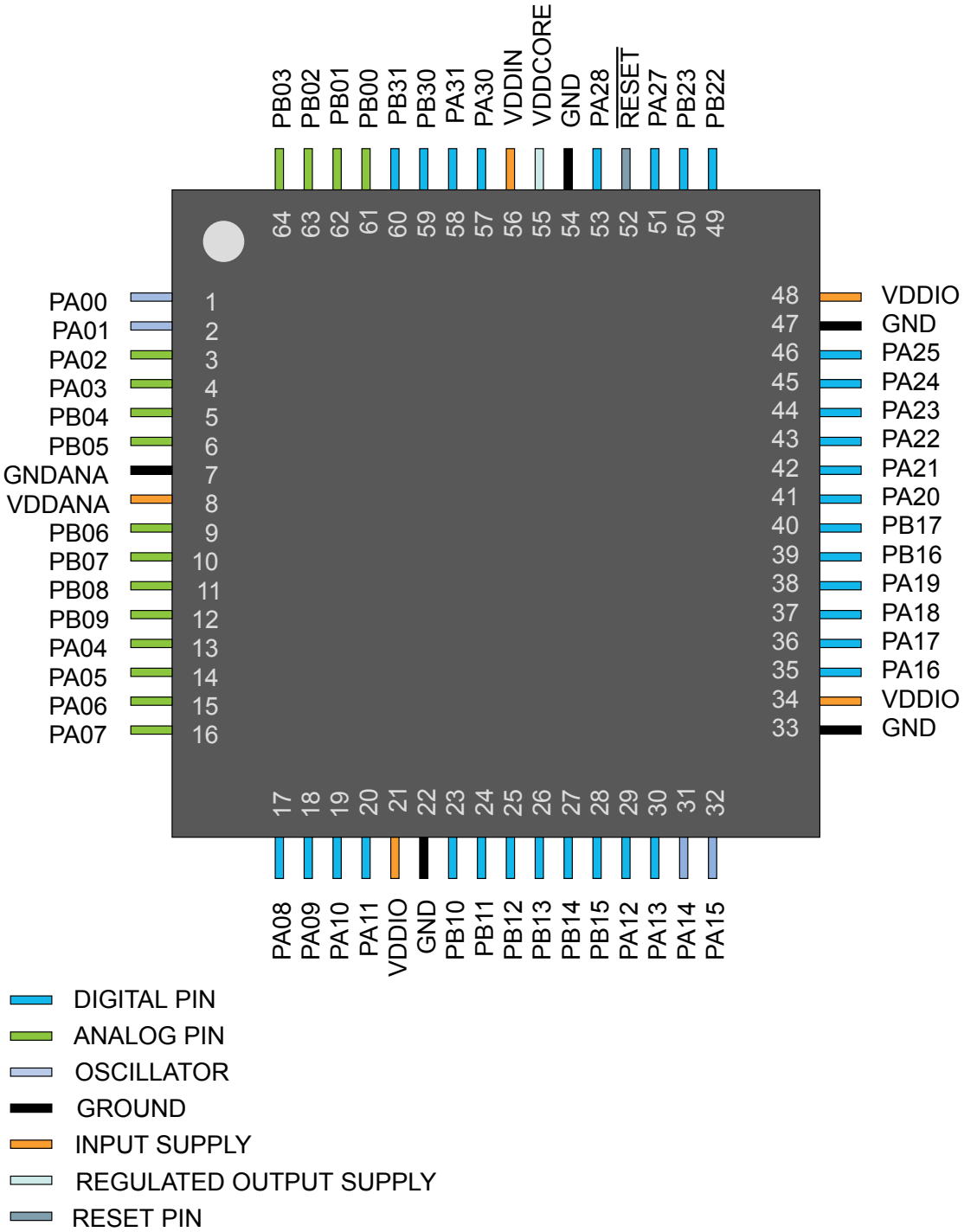


Note: 1. Some products have different number of SERCOM instances, Timer/Counter instances, PTC signals and ADC signals. Refer to *Peripherals Configuration Summary* for details.

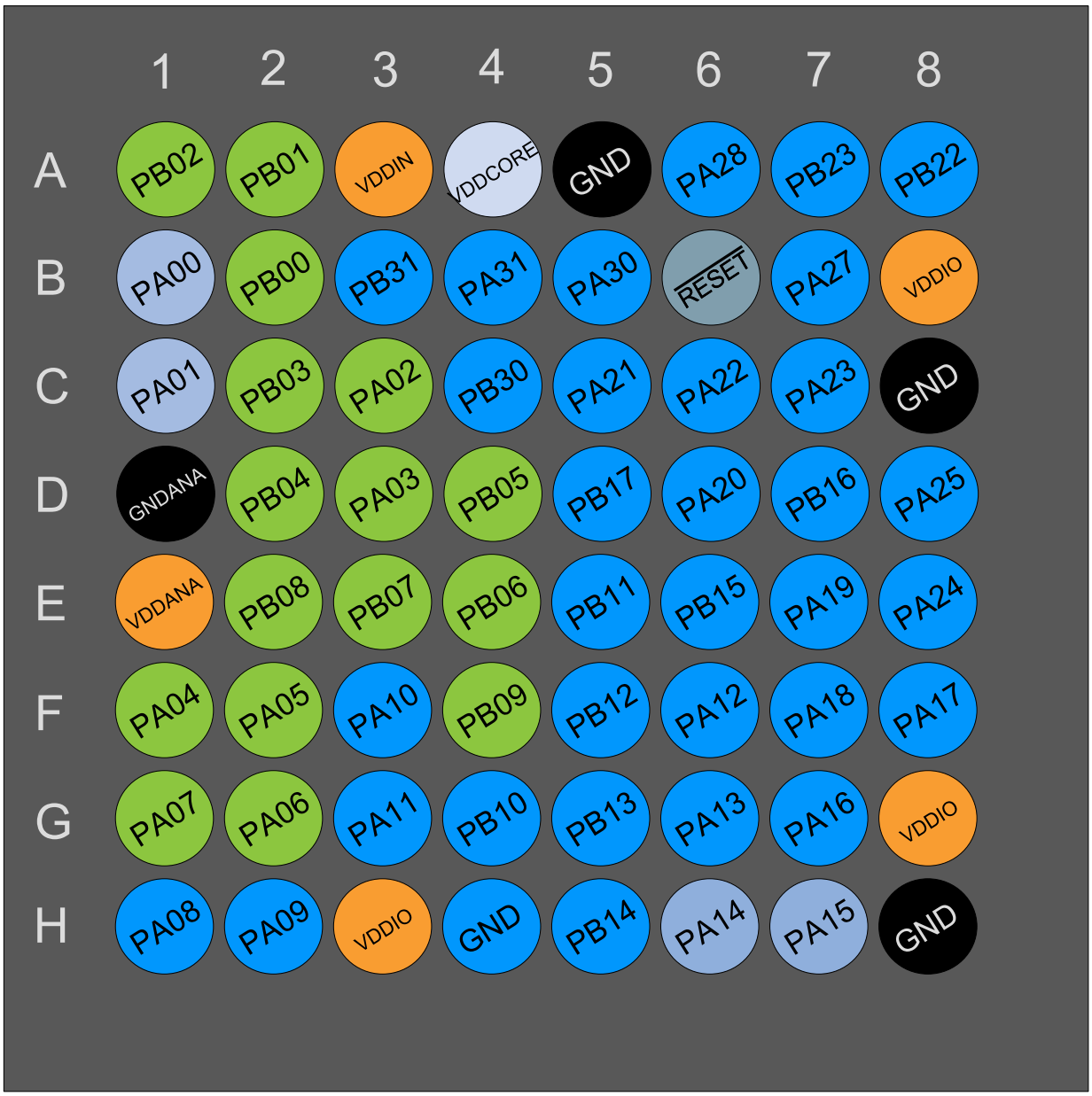
5. Pinout

5.1. SAM D20J

5.1.1. QFN64 / TQFP64



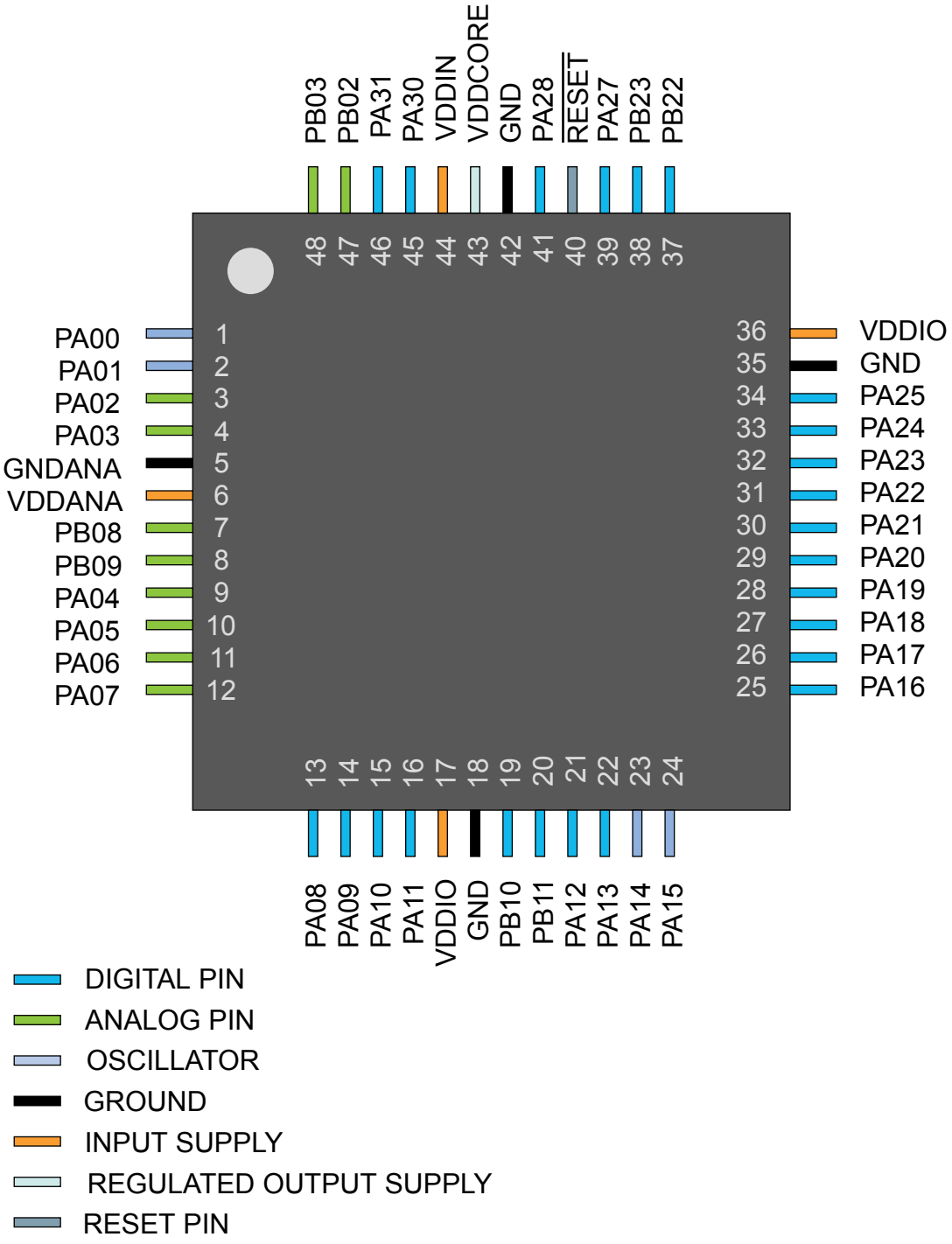
5.1.2. UFBGA64



- DIGITAL PIN
- ANALOG PIN
- OSCILLATOR
- GROUND
- INPUT SUPPLY
- REGULATED OUTPUT SUPPLY
- RESET PIN

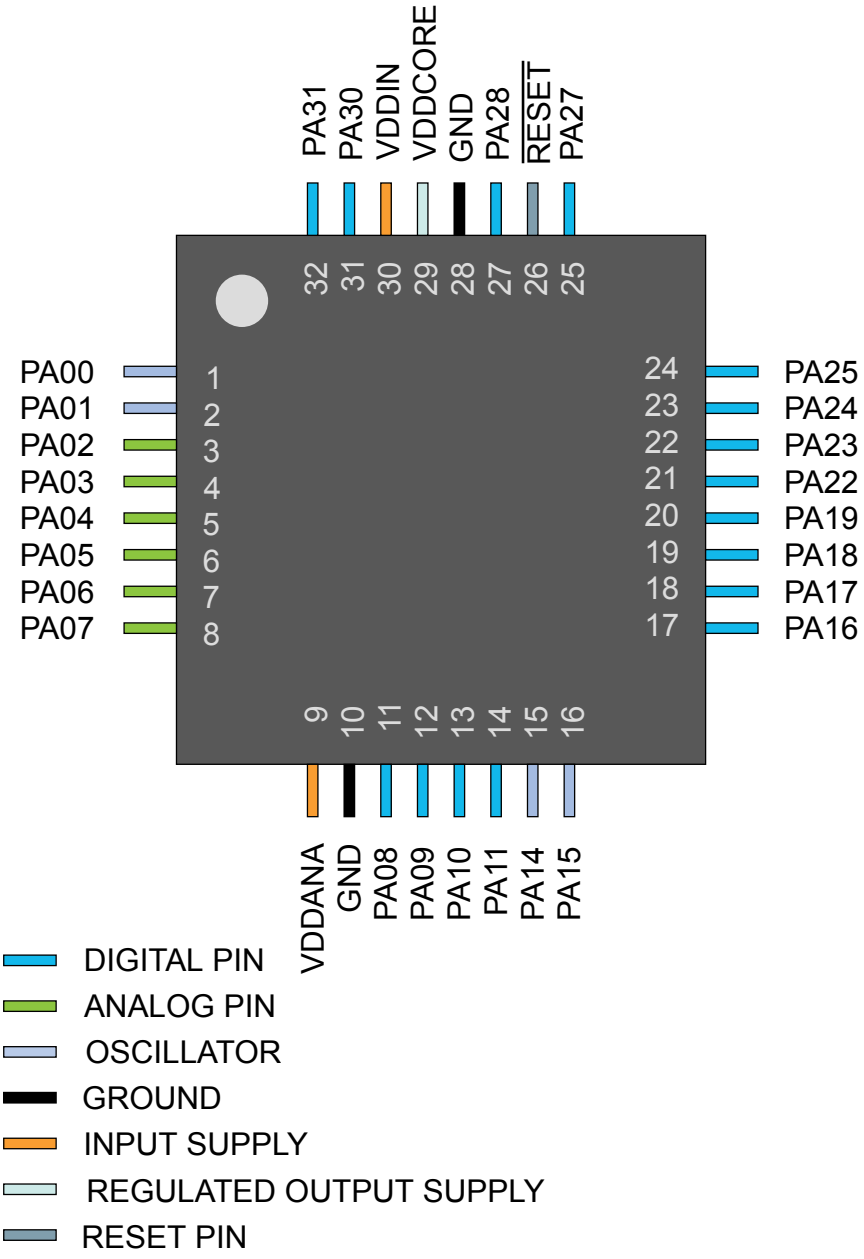
5.2. SAM D20G

5.2.1. QFN48 / TQFP48



5.3. SAM D20E

5.3.1. QFN32 / TQFP32



  - The System Timer is a 24-bit timer that extends the functionality of both the processor and the NVIC. Refer to the Cortex-M0+ Technical Reference Manual for details (www.arm.com).
- Nested Vectored Interrupt Controller (NVIC)
  - External interrupt signals connect to the NVIC, and the NVIC prioritizes the interrupts. Software can set the priority of each interrupt. The NVIC and the Cortex-M0+ processor core are closely coupled, providing low latency interrupt processing and efficient processing of late arriving interrupts. Refer to Nested Vector Interrupt Controller and the Cortex-M0+ Technical Reference Manual for details (www.arm.com).
- System Control Block (SCB)
  - The System Control Block provides system implementation information, and system control. This includes configuration, control, and reporting of the system exceptions. Refer to the Cortex-M0+ Devices Generic User Guide for details (www.arm.com).
- Micro Trace Buffer (MTB)
  - The CoreSight MTB-M0+ (MTB) provides a simple execution trace capability to the Cortex-M0+ processor. Refer to section Micro Trace Buffer and the CoreSight MTB-M0+ Technical Reference Manual for details (www.arm.com).

7.1.3. Cortex-M0+ Address Map

Table 7-2. Cortex-M0+ Address Map

Address	Peripheral
0xE000E000	System Control Space (SCS)
0xE000E010	System Timer (SysTick)
0xE000E100	Nested Vectored Interrupt Controller (NVIC)
0xE000ED00	System Control Block (SCB)
0x41006000 (see also Product Mapping)	Micro Trace Buffer (MTB)

7.1.4. I/O Interface

7.1.4.1. Overview

Because accesses to the AMBA® AHB-Lite™ and the single cycle I/O interface can be made concurrently, the Cortex-M0+ processor can fetch the next instructions while accessing the I/Os. This enables single cycle I/O accesses to be sustained for as long as needed. Refer to *CPU Local Bus* for more information.

7.1.4.2. Description

Direct access to PORT registers.

7.2. Nested Vector Interrupt Controller

7.2.1. Overview

The Nested Vectored Interrupt Controller (NVIC) in the SAM D20 supports 32 interrupt lines with four different priority levels. For more details, refer to the Cortex-M0+ Technical Reference Manual (www.arm.com).

7.2.2. Interrupt Line Mapping

Each of the 28 interrupt lines is connected to one peripheral instance, as shown in the table below. Each peripheral can have one or more interrupt flags, located in the peripheral's Interrupt Flag Status and Clear

(INTFLAG) register. The interrupt flag is set when the interrupt condition occurs. Each interrupt in the peripheral can be individually enabled by writing a one to the corresponding bit in the peripheral's Interrupt Enable Set (INTENSET) register, and disabled by writing a one to the corresponding bit in the peripheral's Interrupt Enable Clear (INTENCLR) register. An interrupt request is generated from the peripheral when the interrupt flag is set and the corresponding interrupt is enabled. The interrupt requests for one peripheral are ORed together on system level, generating one interrupt request for each peripheral. An interrupt request will set the corresponding interrupt pending bit in the NVIC interrupt pending registers (SETPEND/CLRPEND bits in ISPR/ICPR). For the NVIC to activate the interrupt, it must be enabled in the NVIC interrupt enable register (SETENA/CLRENA bits in ISER/ICER). The NVIC interrupt priority registers IPR0-IPR7 provide a priority field for each interrupt.

Table 7-3. Interrupt Line Mapping

Peripheral Source	NVIC Line
EIC NMI – External Interrupt Controller	NMI
PM – Power Manager	0
SYSCTRL – System Control	1
WDT – Watchdog Timer	2
RTC – Real Time Counter	3
EIC – External Interrupt Controller	4
NVMCTRL – Non-Volatile Memory Controller	5
EVSYS – Event System	6
SERCOM0 – Serial Communication Interface 0	7
SERCOM1 – Serial Communication Interface 1	8
SERCOM2 – Serial Communication Interface 2	9
SERCOM3 – Serial Communication Interface 3	10
SERCOM4 – Serial Communication Interface 4	11
SERCOM5 – Serial Communication Interface 5	12
TC0 – Timer Counter 0	13
TC1 – Timer Counter 1	14
TC2 – Timer Counter 2	15
TC3 – Timer Counter 3	16
TC4 – Timer Counter 4	17
TC5 – Timer Counter 5	18
TC6 – Timer Counter 6	19
TC7 – Timer Counter 7	20
ADC – Analog-to-Digital Converter	21
AC – Analog Comparator	22

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 3 – GCLK
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 2 – SYSCTRL
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 1 – PM
Writing a zero to these bits has no effect.

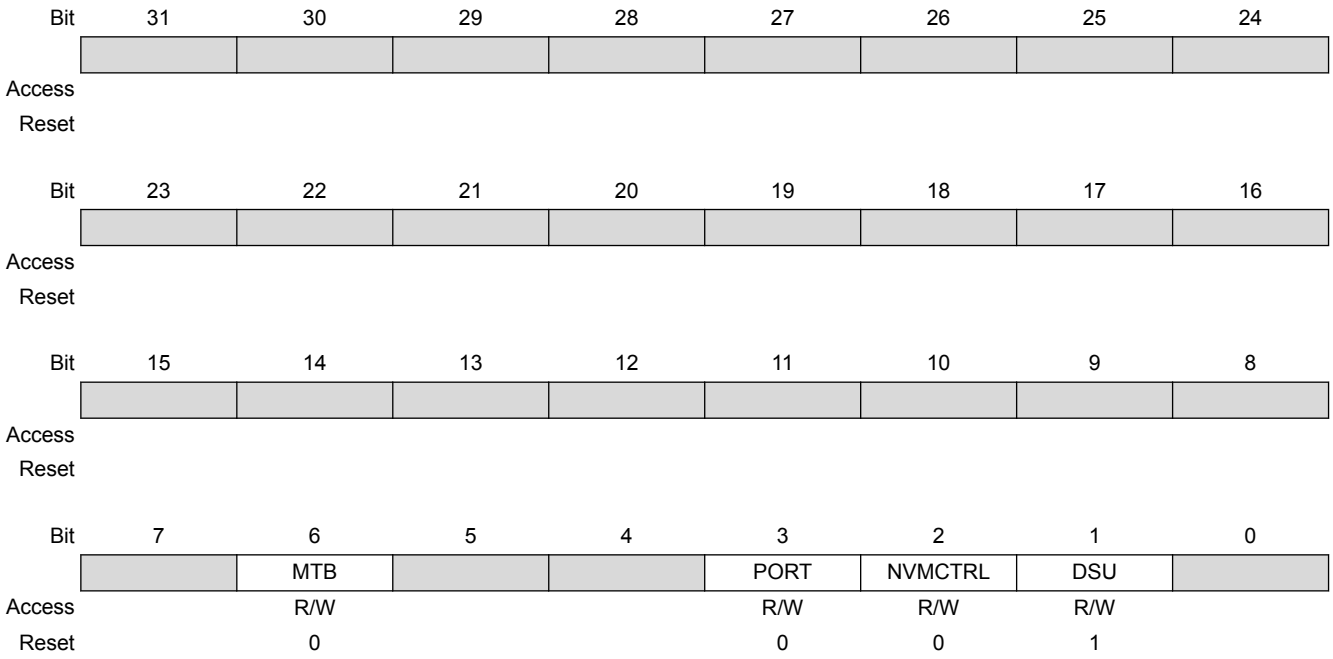
Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

7.7.2. PAC1 Register Description

7.7.2.1. Write Protect Clear

Name: WPCLR
Offset: 0x00
Reset: 0x000002
Property: –



Bit 6 – MTB
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 3 – PORT
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 2 – NVMCTRL
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 1 – DSU
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 1 – DSU
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

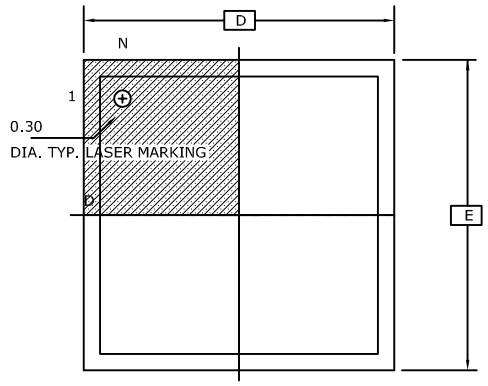
7.7.3. PAC2 Register Description

Table 8-4. Package Reference

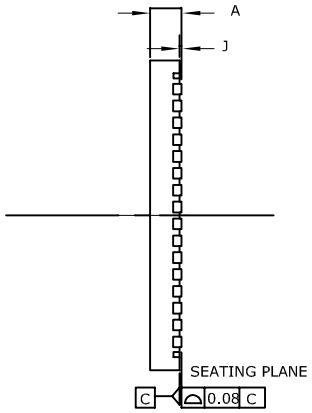
JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

8.2.2. 64 pin QFN

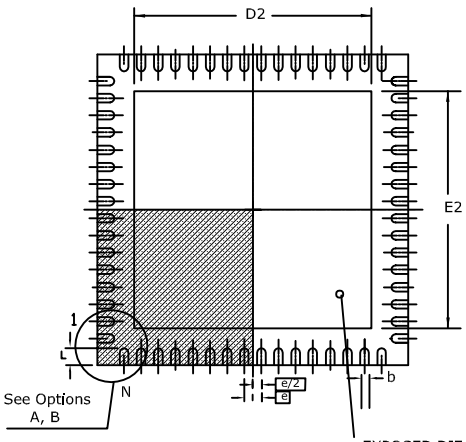
DRAWINGS NOT SCALED



TOP VIEW



SIDE VIEW

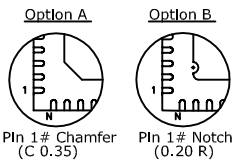


BOTTOM VIEW

COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.80	-----	1.00	
D/E		9.00 BSC		
D2/E2	4.60	4.70	4.80	
J	0.00	-----	0.05	
b	0.15	0.20	0.25	
e		0.50 BSC		
L	0.30	0.40	0.55	
N		64		



Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MO-220, Variation VMMD-4, for proper dimensions, tolerances, datums, etc.
2. Dimension b applies to metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
If the terminal has the optical radius on the other end of the terminal, the dimension should not be measured in that radius area.

05/27/2011

	TITLE	GPC	DRAWING NO.	REV.
Package Drawing Contact: packagedrawings@atmel.com	PA, 64 Leads , 0.50 mm pitch, 9 x 9 x 1 mm Very Thin Quad Flat No Lead Package (VQFN) Sawn	ZST	PA	A

Note: The exposed die attach pad is not connected electrically inside the device.

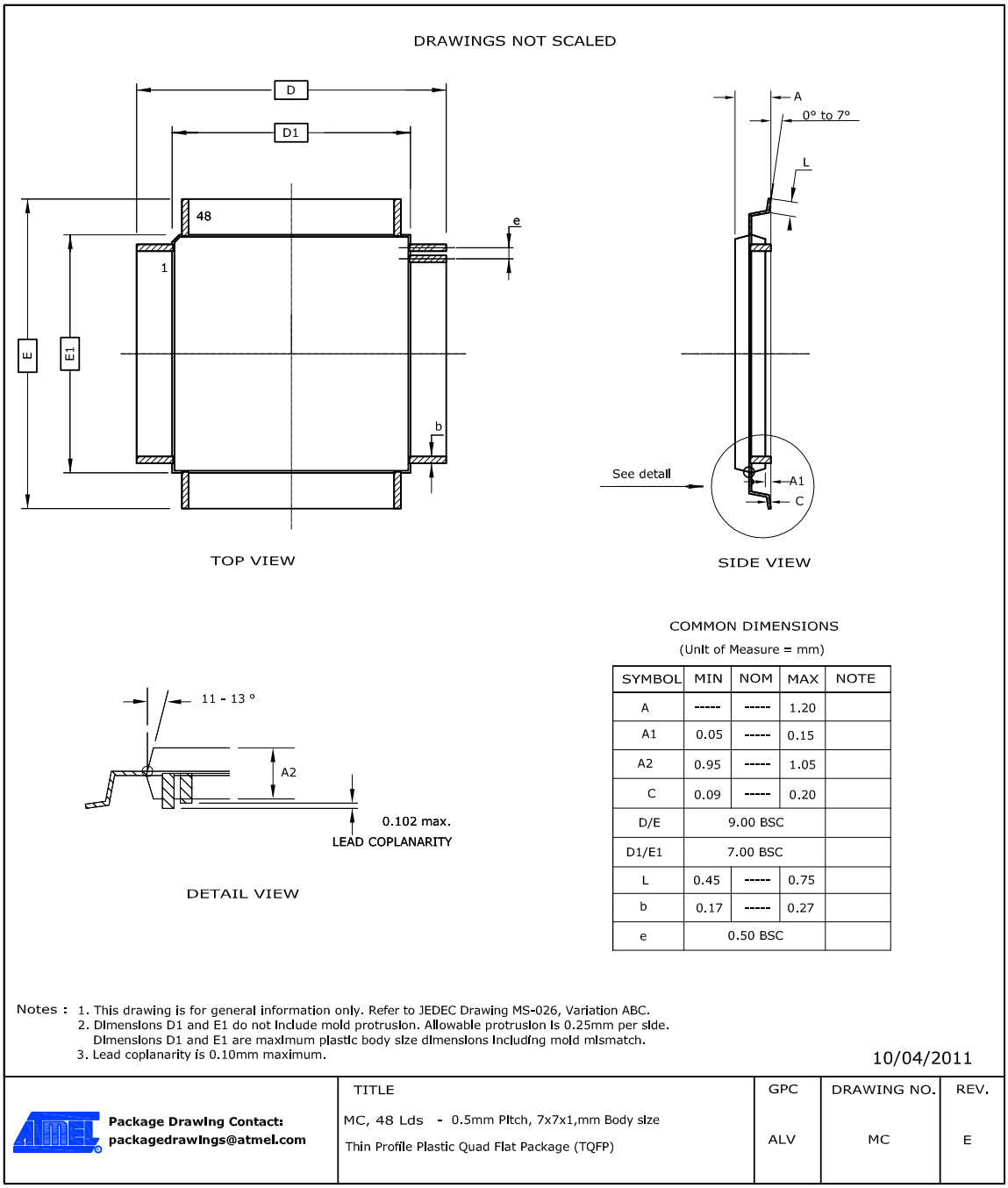
Table 8-9. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-10. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E8

8.2.4. 48 pin TQFP



COMMON DIMENSIONS

(Unit of Measure = mm)

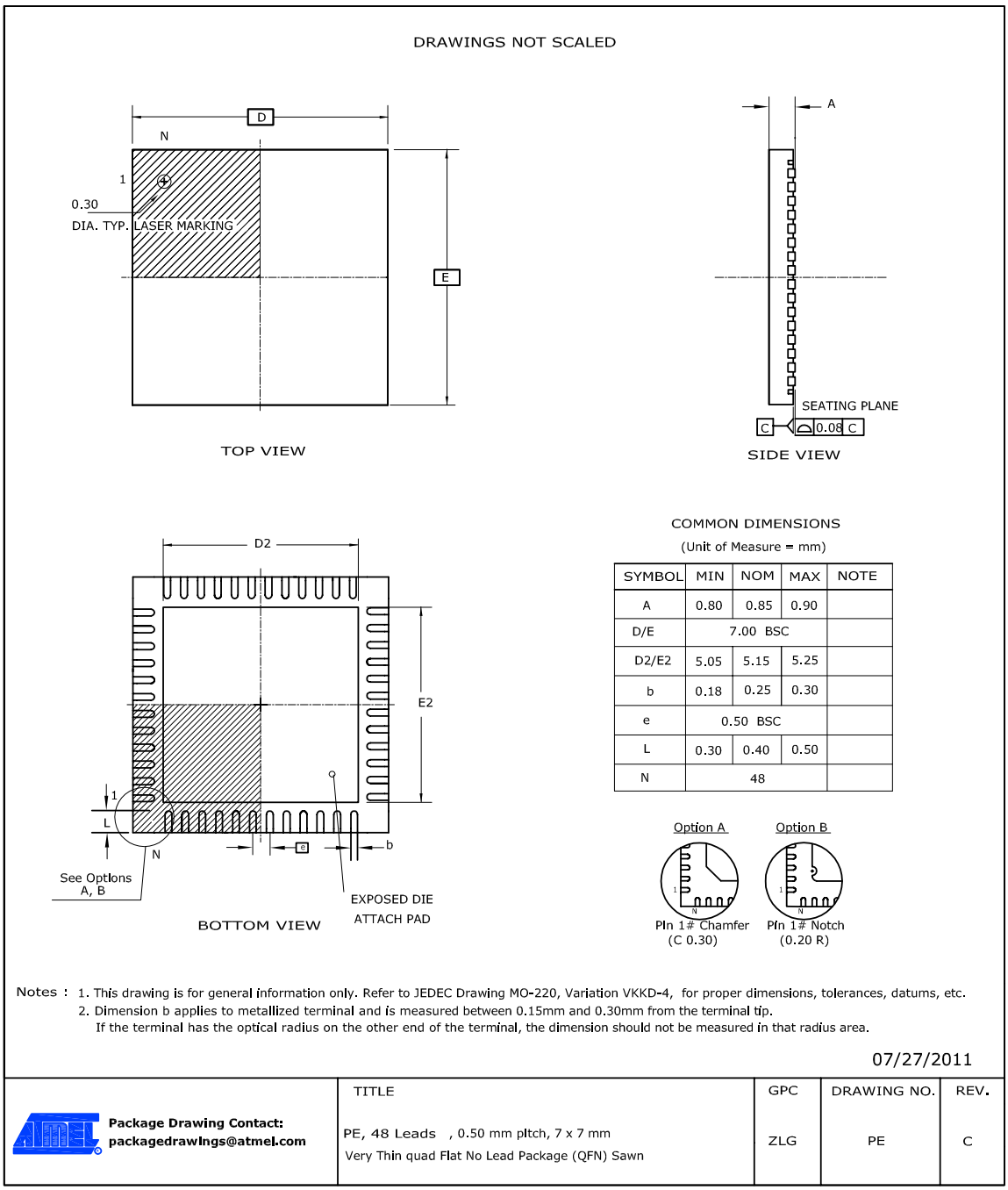
SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	1.20	
A1	0.05	-----	0.15	
A2	0.95	-----	1.05	
C	0.09	-----	0.20	
D/E		9.00 BSC		
D1/E1		7.00 BSC		
L	0.45	-----	0.75	
b	0.17	-----	0.27	
e		0.50 BSC		

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MS-026, Variation ABC.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

10/04/2011

	TITLE	GPC	DRAWING NO.	REV.
Package Drawing Contact: packagedrawings@atmel.com	MC, 48 Lds - 0.5mm Pitch, 7x7x1,mm Body size Thin Profile Plastic Quad Flat Package (TQFP)	ALV	MC	E

8.2.5. 48 pin QFN



SYMBOL	MIN	NOM	MAX	NOTE
A	0.80	0.85	0.90	
D/E		7.00 BSC		
D2/E2	5.05	5.15	5.25	
b	0.18	0.25	0.30	
e		0.50 BSC		
L	0.30	0.40	0.50	
N		48		

Note: The exposed die attach pad is not connected electrically inside the device.

Table 8-14. Device and Package Maximum Weight

140	mg

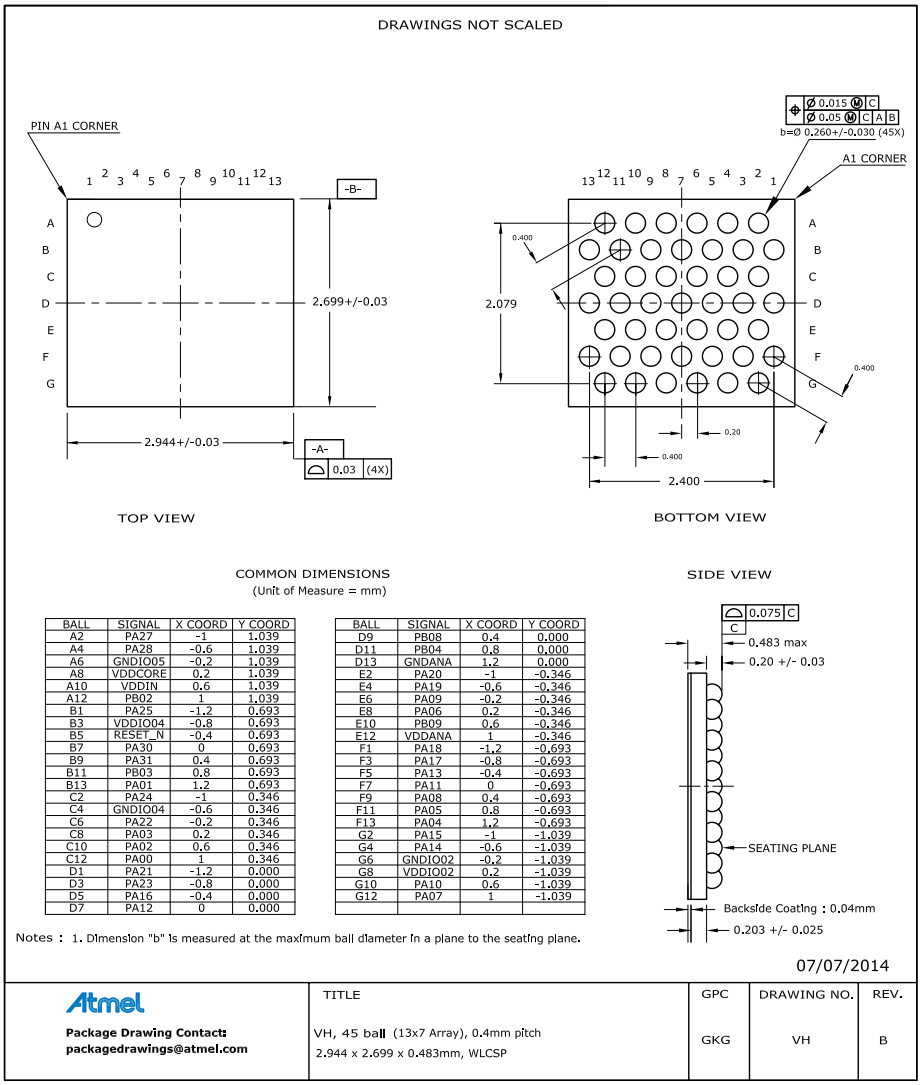
Table 8-15. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-16. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

8.2.6. 45-ball WLCSP



BALL	SIGNAL	X COORD	Y COORD
A2	PA27	-1	1.039
A4	PA28	-0.6	1.039
A6	GNDIO05	-0.2	1.039
A8	VDDCORE	0.2	1.039
A10	VDDIN	0.6	1.039
A12	PB02	1	1.039
B1	PA25	-1.2	0.693
B3	VDDIO04	-0.8	0.693
B5	RESET_N	-0.4	0.693
B7	PA30	0	0.693
B9	PA31	0.4	0.693
B11	PB03	0.8	0.693
B13	PA01	1.2	0.693
C2	PA24	-1	0.346
C4	GNDIO04	-0.6	0.346
C6	PA22	-0.2	0.346
C8	PA03	0.2	0.346
C10	PA02	0.6	0.346
C12	PA00	1	0.346
D1	PA21	-1.2	0.000
D3	PA23	-0.8	0.000
D5	PA16	-0.4	0.000
D7	PA12	0	0.000

BALL	SIGNAL	X COORD	Y COORD
D9	PB08	0.4	0.000
D11	PB04	0.8	0.000
D13	GNDANA	1.2	0.000
E2	PA20	-1	-0.346
E4	PA19	-0.6	-0.346
E6	PA09	-0.2	-0.346
E8	PA06	0.2	-0.346
E10	PB09	0.6	-0.346
E12	VDDANA	1	-0.346
F1	PA18	-1.2	-0.693
F3	PA17	-0.8	-0.693
F5	PA13	-0.4	-0.693
F7	PA11	0	-0.693
F9	PA08	0.4	-0.693
F11	PA05	0.8	-0.693
F13	PA04	1.2	-0.693
G2	PA15	-1	-1.039
G4	PA14	-0.6	-1.039
G6	GNDIO02	-0.2	-1.039
G8	VDDIO02	0.2	-1.039
G10	PA10	0.6	-1.039
G12	PA07	1	-1.039

Table 8-17. Device and Package Maximum Weight

7.3	mg

Table 8-18. Package Characteristics

Moisture Sensitivity Level	MSL1

Table 8-19. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E1

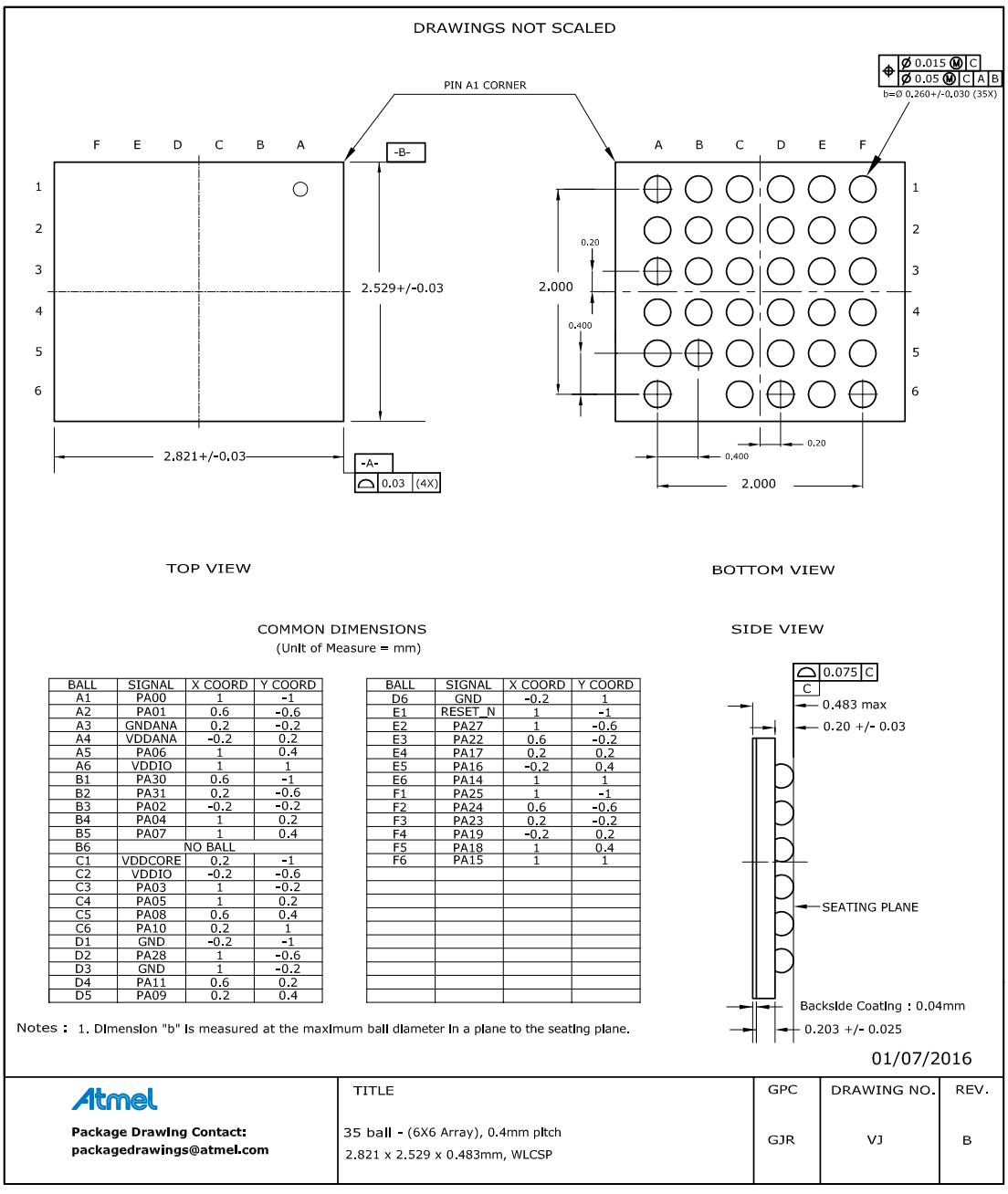
Table 8-24. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-25. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

8.2.9. 35 ball WLCSP



BALL	SIGNAL	X COORD	Y COORD
A1	PA00	1	-1
A2	PA01	0.6	-0.6
A3	GNDANA	0.2	-0.2
A4	VDDANA	-0.2	0.2
A5	PA06	1	0.4
A6	VDDIO	1	1
B1	PA30	0.6	-1
B2	PA31	0.2	-0.6
B3	PA02	-0.2	-0.2
B4	PA04	1	0.2
B5	PA07	1	0.4
B6	NO BALL		
C1	VDDCORE	0.2	-1
C2	VDDIO	-0.2	-0.6
C3	PA03	1	-0.2
C4	PA05	1	0.2
C5	PA08	0.6	0.4
C6	PA10	0.2	1
D1	GND	-0.2	-1
D2	PA28	1	-0.6
D3	GND	1	-0.2
D4	PA11	0.6	0.2
D5	PA09	0.2	0.4

BALL	SIGNAL	X COORD	Y COORD
D6	GND	-0.2	1
E1	RESET_N	1	-1
E2	PA27	1	-0.6
E3	PA22	0.6	-0.2
E4	PA17	0.2	0.2
E5	PA16	-0.2	0.4
E6	PA14	1	1
F1	PA25	1	-1
F2	PA24	0.6	-0.6
F3	PA23	0.2	-0.2
F4	PA19	-0.2	0.2
F5	PA18	1	0.4
F6	PA15	1	1

Table 8-26. Device and Package Maximum Weight

6.2	mg

Table 8-27. Package Characteristics

Moisture Sensitivity Level	MSL1

Table 8-28. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E1

8.3. Soldering Profile

The following table gives the recommended soldering profile from J-STD-20.

Table 8-29.

Profile Feature	Green Package
Average Ramp-up Rate (217°C to peak)	3°C/s max.
Preheat Temperature 175°C ±25°C	150-200°C
Time Maintained Above 217°C	60-150s
Time within 5°C of Actual Peak Temperature	30s
Peak Temperature Range	260°C
Ramp-down Rate	6°C/s max.
Time 25°C to Peak Temperature	8 minutes max.

A maximum of three reflow passes is allowed per component.